# **DRA5143E**

## Silicon PNP epitaxial planar type

For digital circuits Complementary to DRC5143E DRA2143E in SMini3 type package

#### ■ Features

- $\bullet$  Low collector-emitter saturation voltage  $V_{\text{CE(sat)}}$
- Halogen-free / RoHS compliant
   (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

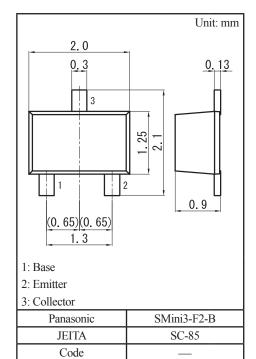
### ■ Marking Symbol: L5

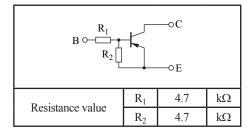
### ■ Packaging

DRA5143E0L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

## ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	-50	V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	-50	V
Collector current	$I_{C}$	-100	mA
Total power dissipation	P <sub>T</sub>	150	mW
Junction temperature	$T_{j}$	150	°C
Storage temperature	T <sub>stg</sub>	-55 to +150	°C

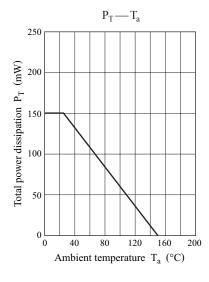


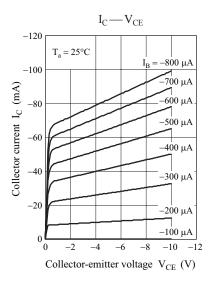


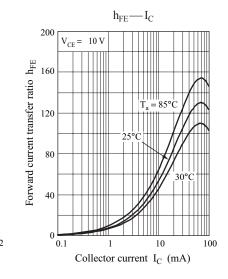
## ■ Electrical Characteristics $T_a = 25$ °C±3°C

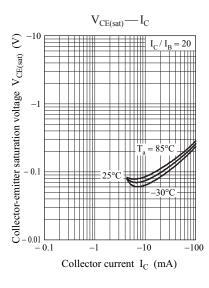
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_{\rm C} = -10  \mu A, I_{\rm E} = 0$	-50			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_C = -2 \text{ mA}, I_B = 0$	-50			V
Collector-base cutoff current (Emitter open)	I <sub>CBO</sub>	$V_{CB} = -50 \text{ V}, I_E = 0$			-0.1	μΑ
Collector-emitter cutoff current (Base open)	I <sub>CEO</sub>	$V_{CE} = -50 \text{ V}, I_{B} = 0$			-0.5	μΑ
Emitter-base cutoff current (Collector open)	$I_{EBO}$	$V_{EB} = -6 \text{ V}, I_C = 0$			-2.0	mA
Forward current transfer ratio	$h_{\mathrm{FE}}$	$V_{CE} = -10 \text{ V}, I_{C} = -5 \text{ mA}$	20			_
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = -10 \text{ mA}, I_B = -0.5 \text{ mA}$			-0.25	V
Input voltage (ON)	V <sub>I(on)</sub>	$V_{CE} = -0.2 \text{ V}, I_{C} = -5 \text{ mA}$	-1.9			V
Input voltage (OFF)	V <sub>I(off)</sub>	$V_{CE} = -5 \text{ V}, I_{C} = -100 \mu\text{A}$			-0.8	V
Input resistance	R <sub>1</sub>		-30%	4.7	+30%	kΩ
Resistance ratio	$R_1/R_2$		0.8	1.0	1.2	_

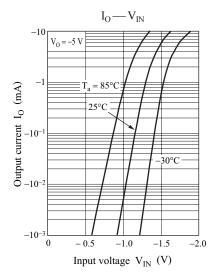
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

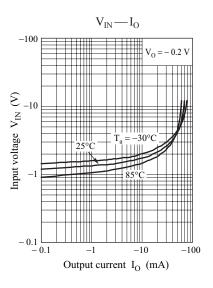








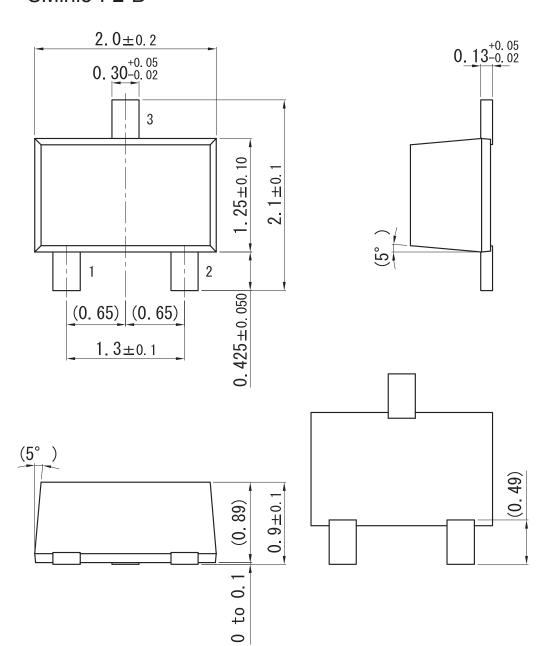




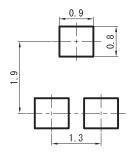
Ver. DED 2

## SMini3-F2-B

Unit: mm



## ■ Land Pattern (Reference) (Unit: mm)



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